

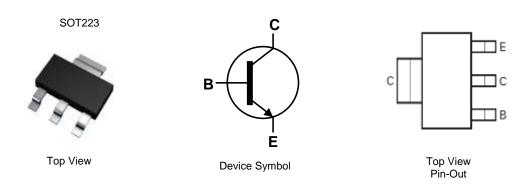
#### 150V NPN MEDIUM POWER TRANSISTOR IN SOT223

#### **Features**

- BV<sub>CEO</sub> > 150V
- I<sub>C</sub> = 5A High Continuous Collector Current
- I<sub>CM</sub> = 10A Peak Pulse Current
- Very Low Saturation Voltage V<sub>CE(SAT)</sub> < 110mV @ 1A
- $R_{CE(SAT)} = 50m\Omega$  for a Low Equivalent On-Resistance
- hFE Specified Up to 10A for a High Gain Hold-Up
- Complementary PNP Type: FZT955
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

- Case: SOT223
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 (#\$)
- Weight: 0.112 grams (Approximate)



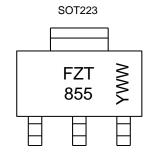
#### **Ordering Information** (Note 4)

Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
FZT855TA	FZT855	7	12	1,000

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

#### **Marking Information**



FZT 855 = Product Type Marking Code YWW = Date Code Marking Y or  $\overline{Y}$  = Last Digit of Year (ex: 7 = 2017) WW or  $\overline{W}W = \text{Week Code } (01-53)$ 



### Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	250	V
Collector-Emitter Voltage	V <sub>CEO</sub>	150	V
Emitter-Base Voltage	$V_{EBO}$	7	V
Continuous Collector Current	Ic	5	Α
Peak Pulse Current	I <sub>CM</sub>	10	Α
Base Current	I <sub>B</sub>	1	Α

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Power Dissipation	(Note 5)		3.0 24	W mW/°C	
Linear Derating Factor	(Note 6)	- P <sub>D</sub>	1.6 12.8		
Thermal Desigtance Junction to Ambient	(Note 5)	$R_{\theta JA}$	42		
Thermal Resistance, Junction to Ambient	(Note 6)	R <sub>0JA</sub>	78	°C/W	
Thermal Resistance Junction to Lead (Note 7)		R <sub>0</sub> JL	8.8		
Operating and Storage Temperature Range	$T_{J_i} T_{STG}$	-55 to +150	°C		

### ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	≥ 8,000	V	3B
Electrostatic Discharge - Machine Model	ESD MM	≥ 400	V	С

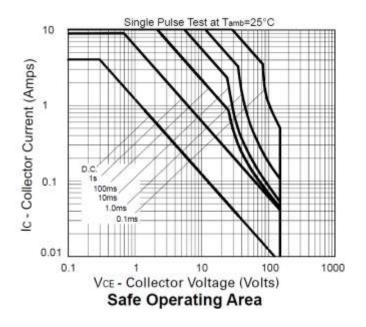
Notes:

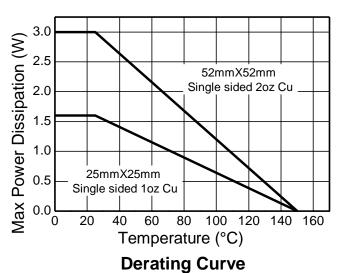
- 5. For a device surface mounted on 52mm X 52mm FR4 PCB with high coverage of single sided 2oz copper, in still air conditions; device measured when operating in steady state condition.

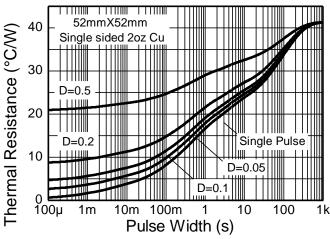
  6. Same as Note 5, except the device is mounted on 25mm x 25mm single sided 1oz weight copper.
- 8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

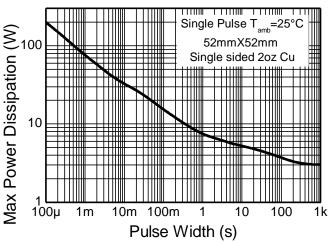


#### **Thermal Characteristics and Derating Information**









**Transient Thermal Impedance** 

**Pulse Power Dissipation** 



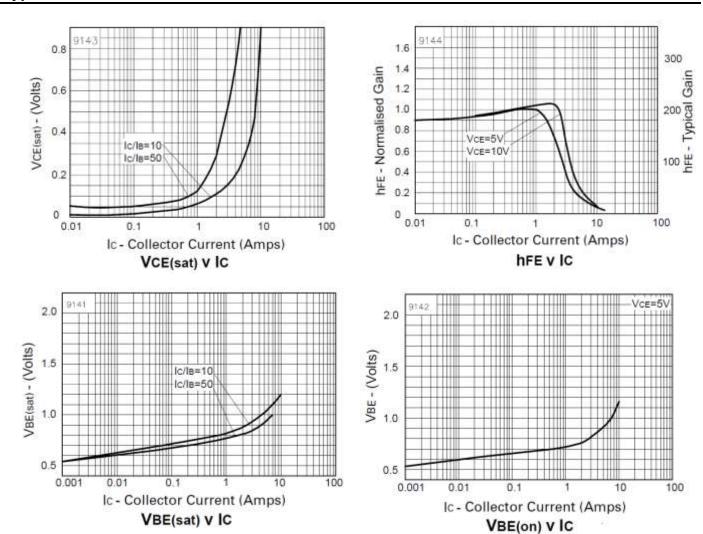
## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	250	375	_	V	$I_{C} = 100 \mu A$
Collector-Emitter Breakdown Voltage	BV <sub>CER</sub>	250	375		V	$I_C = 1\mu A, R_B \le 1k\Omega$
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	150	180	_	V	$I_C = 1mA$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	7	8		V	$I_E = 100\mu A$
Collector Cut-Off Current	I <sub>CBO</sub>	_	_	50 1	nΑ μΑ	V <sub>CB</sub> = 200V V <sub>CB</sub> = 200V, @T <sub>A</sub> = +100°C
Collector Cut-Off Current	I <sub>CER</sub>	_	_	50 1	nΑ μΑ	$V_{CE}$ = 200V, R ≤ 1kΩ $V_{CE}$ = 200V, @T <sub>A</sub> = +100°C
Emitter Cut-Off Current	I <sub>EBO</sub>	_	_	10	nA	$V_{EB} = 6V$
Collector-Emitter Saturation Voltage (Note 9)	V <sub>CE(SAT)</sub>	_	20 35 60 260	40 65 110 355	mV	$I_C = 100$ mA, $I_B = 5$ mA $I_C = 500$ mA, $I_B = 50$ mA $I_C = 1$ A, $I_B = 100$ mA $I_C = 5$ A, $I_B = 500$ mA
Base-Emitter Saturation Voltage (Note 9)	V <sub>BE(SAT)</sub>	_	_	1,250	mV	I <sub>C</sub> =5A, I <sub>B</sub> = 500mA
Base-Emitter Turn-On Voltage (Note 9)	V <sub>BE(ON)</sub>	_	_	1,100	mV	$I_{C} = 5A, V_{CE} = 5V$
DC Current Gain (Note 9)	h <sub>FE</sub>	100 100 15 —	200 200 30 10	300 — —		$I_{C} = 10 \text{mA}, V_{CE} = 5 \text{V}$ $I_{C} = 1 \text{A}, V_{CE} = 5 \text{V}$ $I_{C} = 5 \text{A}, V_{CE} = 5 \text{V}$ $I_{C} = 10 \text{A}, V_{CE} = 5 \text{V}$
Current Gain-Bandwidth Product (Note 9)	f <sub>T</sub>	_	90	_	MHz	$V_{CE} = 10V, I_{C} = 100mA$ f = 50MHz
Output Capacitance	Сово	_	22		pF	V <sub>CB</sub> = 10V, f = 1MHz
Switching Times	t <sub>ON</sub> toff	_	66 2,130	_	ns ns	$I_C = 1A$ , $V_{CC} = 50V$ $I_{B1} = -I_{B2} = 100mA$

Note: 9. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%.



## Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)





# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

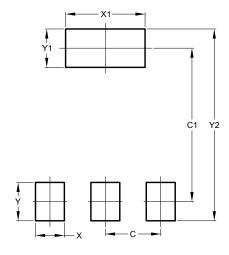
# 

SOT223					
Dim	Min	Max	Тур		
Α	1.55	1.65	1.60		
A1	0.010	0.15	0.05		
b	0.60	0.80	0.70		
b1	2.90	3.10	3.00		
С	0.20	0.30	0.25		
D	6.45	6.55	6.50		
Е	3.45	3.55	3.50		
E1	6.90	7.10	7.00		
е	-	-	4.60		
e1	-	-	2.30		
L	0.85	1.05	0.95		
Q	0.84	0.94	0.89		
All Dimensions in mm					

## **Suggested Pad Layout**

 $\label{prop:lease} Please see \ http://www.diodes.com/package-outlines.html for the latest version.$ 

#### **SOT223**



Dimensions	Value (in mm)
С	2.30
C1	6.40
Х	1.20
X1	3.30
Υ	1.60
Y1	1.60
Y2	8.00

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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